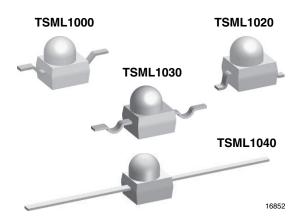
# TSML1000, TSML1020, TSML1030, TSML1040

Vishay Semiconductors

# High Power Infrared Emitting Diode, 940 nm, GaAlAs, MQW



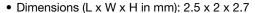
### **DESCRIPTION**

TSML1000 is an infrared, 940 nm emitting diode in GaAlAs multi quantum well (MQW) technology with high radiant power and high speed molded in a clear, untinted plastic package (with lens) for surface mounting (SMD).

### **FEATURES**

· Package type: surface-mount





• Peak wavelength:  $\lambda_p = 940 \text{ nm}$ 

High radiant power

High radiant intensity

• Angle of half intensity:  $\phi = \pm 12^{\circ}$ 

Low forward voltage

· Suitable for high pulse current operation

· Good spectral matching with Si photodetectors

• Versatile terminal configurations

Package matches with detector TEMT1000

• Floor life: 168 h, MSL 3, according to J-STD-020

 Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

### **APPLICATIONS**

- · For remote control
- Encoder
- Photointerrupters

PRODUCT SUMMARY				
COMPONENT	$I_e$ (mW/sr) at $I_F$ = 20 mA	φ <b>(°)</b>	λ <sub>P</sub> (nm)	t <sub>r</sub> (ns)
TSML1000	11	± 12	940	15
TSML1020	11	± 12	940	15
TSML1030	11	± 12	940	15
TSML1040	11	± 12	940	15

#### Note

Test conditions see table "Basic Characteristics"

ORDERING INFORMAT	ION		
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
TSML1000	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Reverse gullwing
TSML1020	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Gullwing
TSML1030	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Yoke
TSML1040	Bulk	MOQ: 1000 pcs, 1000 pcs/bulk	Axial leads

#### Note

· MOQ: minimum order quantity



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<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>amb</sub> = 25 °C, unless otherwise specified)					
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT	
Reverse voltage		$V_{R}$	5	V	
Forward current		I <sub>F</sub>	100	mA	
Peak forward current	$t_p/T = 0.5, t_p = 100 \mu s$	I <sub>FM</sub>	200	mA	
Surge forward current	t <sub>p</sub> = 100 μs	I <sub>FSM</sub>	1.0	Α	
Power dissipation		P <sub>V</sub>	160	mW	
Junction temperature		Tj	100	°C	
Operating temperature range		T <sub>amb</sub>	-40 to +85	°C	
Storage temperature range		T <sub>stg</sub>	-40 to +100	°C	
Soldering temperature	According to Fig. 10, J-STD-020	T <sub>sd</sub>	260	°C	
Thermal resistance junction to ambient	EIA / JESD51	R <sub>thJA</sub>	400	K/W	

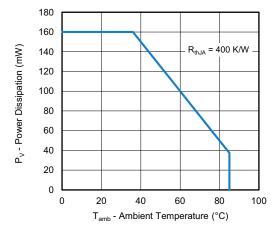


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

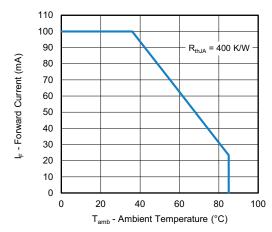


Fig. 2 - Forward Current vs. Ambient Temperature

PARAMETER	CS (T <sub>amb</sub> = 25 °C, unless othe	SYMBOL	MIN.	TYP.	MAX.	UNIT
PARAMETER	TEST CONDITION	STWIDUL	WIIIN.	ITP.	WAX.	UNIT
Forward voltage	$I_F = 20 \text{ mA}, t_p = 20 \text{ ms}$	$V_{F}$	-	1.2	1.5	V
	$I_F = 1 A$ , $t_p = 100 \mu s$	V <sub>F</sub>	-	2.2	-	V
Temperature coefficient of V <sub>F</sub>	I <sub>F</sub> = 1 mA	TK <sub>VF</sub>	-	-1.8	-	mV/K
Reverse current	V <sub>R</sub> = 5 V	I <sub>R</sub>	-	-	10	μΑ
Junction capacitance	V <sub>R</sub> = 0 V, f = 1 MHz, E = 0	Cj	-	40	-	pF
Radiant intensity	$I_F = 20 \text{ mA}, t_p = 20 \text{ ms}$	l <sub>e</sub>	3	11	15	mW/sr
Radiant power	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	фe	-	40	-	mW
Temperature coefficient of φ <sub>e</sub>	I <sub>F</sub> = 20 mA	TKφe	-	-0.6	-	%/K
Angle of half intensity		φ	-	± 12	-	0
Peak wavelength	I <sub>F</sub> = 100 mA	$\lambda_{p}$	-	940	-	nm
Spectral bandwidth	I <sub>F</sub> = 100 mA	Δλ	-	30	-	nm
Temperature coefficient of $\lambda_p$	I <sub>F</sub> = 100 mA	TKλ <sub>p</sub>	-	0.2	-	nm/K
Rise time	I <sub>F</sub> = 100 mA	t <sub>r</sub>	-	15	-	ns
Fall time	I <sub>F</sub> = 100 mA	t <sub>f</sub>	-	15	-	ns

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## **BASIC CHARACTERISTICS** (T<sub>amb</sub> = 25 °C, unless otherwise specified)

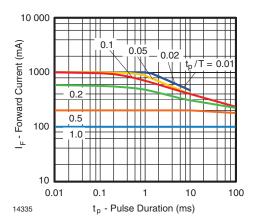


Fig. 3 - Pulse Forward Current vs. Pulse Duration

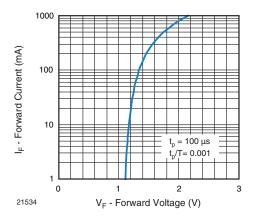


Fig. 4 - Forward Current vs. Forward Voltage

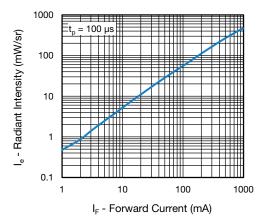


Fig. 5 - Radiant Intensity vs. Forward Current

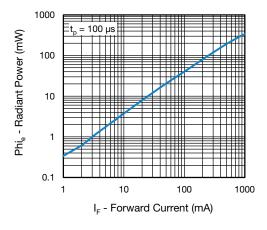


Fig. 6 - Radiant Power vs. Forward Current

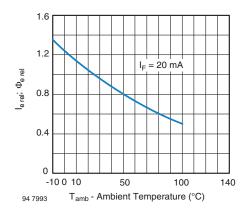


Fig. 7 - Relative Radiant Intensity/Power vs. Ambient Temperature

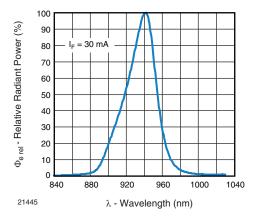


Fig. 8 - Relative Radiant Power vs. Wavelength

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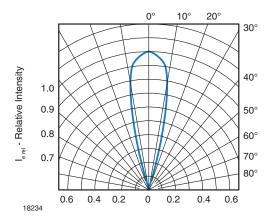


Fig. 9 - Relative Radiant Intensity vs. Angular Displacement

### **PRECAUTIONS FOR USE**

### 1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (burn out will happen).

### 2. Storage

- Storage temperature and rel. humidity conditions are: 5 °C to 35 °C, R.H. 60 %.
- Floor life must not exceed 168 h, according to JEDEC® level 3, J-STD-020.
  - Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp proof box with desiccant.
  - Considering tape life, we suggest to use products within one year from production date.
- If opened more than one week in an atmosphere 5 °C to 35 °C, R.H. 60 %, devices should be treated at 60 °C ± 5 °C for 15 h.
- If humidity indicator in the package shows pink color (normal blue), then devices should be treated with the same conditions as 2.3.

### **REFLOW SOLDER PROFILE**

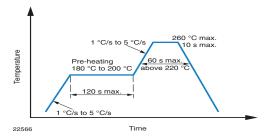


Fig. 10 - Lead (Pb)-Free Reflow Solder Profile According to J-STD-020

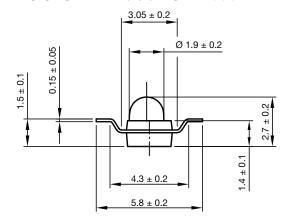
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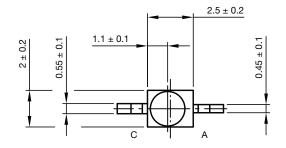


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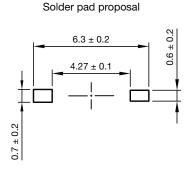
### **PACKAGE DIMENSIONS** in millimeters: TSML1000



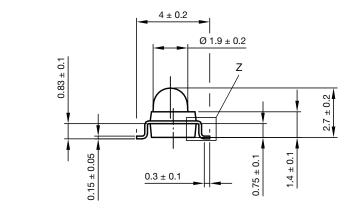




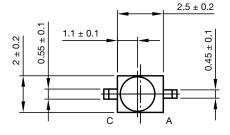
Drawing-No.: 6.544-5326.02-4 Issue: 5; 15.09.2021



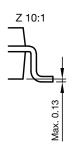
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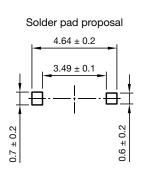






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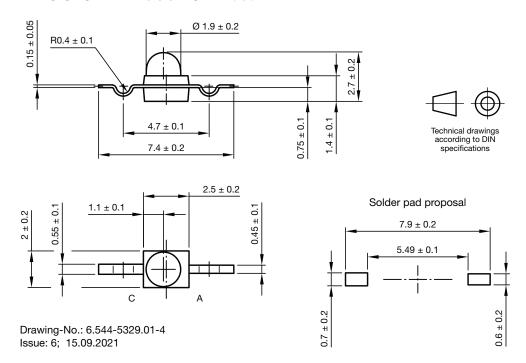




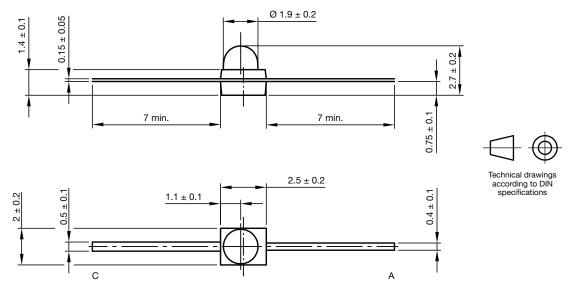


Vishay Semiconductors

### **PACKAGE DIMENSIONS** in millimeters: TSML1030

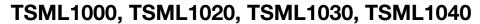


### PACKAGE DIMENSIONS in millimeters: TSML1040



Drawing-No.: 6.544-5339.02-4

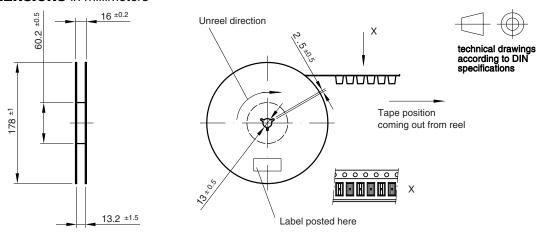
Issue: 4; 04.08.2021



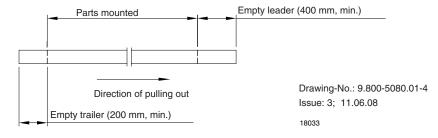


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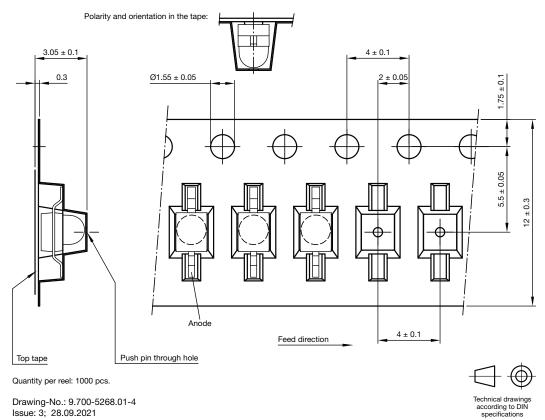
### **REEL DIMENSIONS** in millimeters

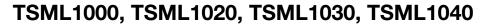


### Leader and trailer tape:



### TAPING DIMENSIONS in millimeters: TSML1000

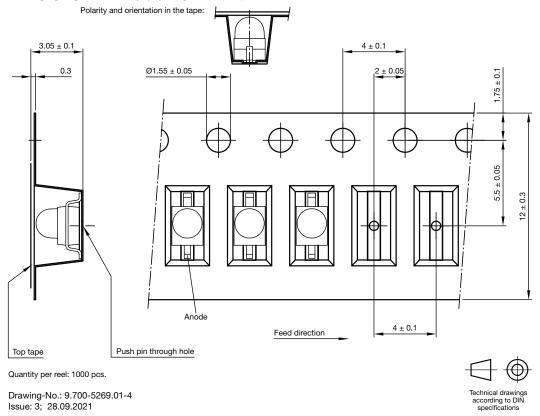




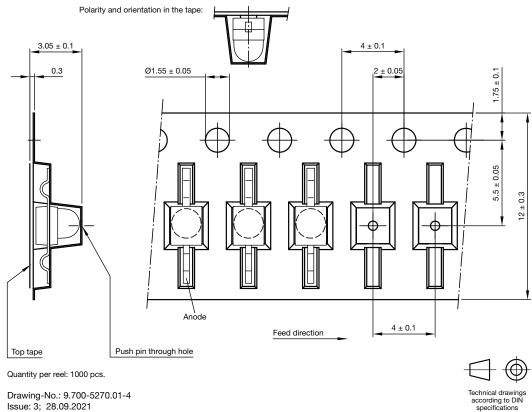


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### TAPING DIMENSIONS in millimeters: TSML1020



### **TAPING DIMENSIONS** in millimeters: **TSML1030**





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